RENESAS

HZM6.2Z4MWA

Silicon Planar Zener Diode for Surge Absorb

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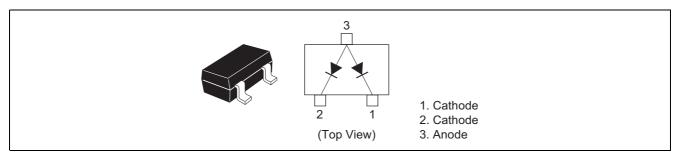
Features

- HZM6.2Z4MWA has two devices in a monolithic, and can absorb surge.
- Low capacitance (C = 4.0 pF Typ / 4.5 pF Max) and can protect ESD of signal line.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HZM6.2Z4MWA	N1	MPAK

Pin Arrangement





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

ltem	Symbol	Value	Unit
Power dissipation	Pd *	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	–55 to +150	°C

Note: Two device total, See Fig.2.

Electrical Characteristics *1

 $(Ta = 25^{\circ}C)$

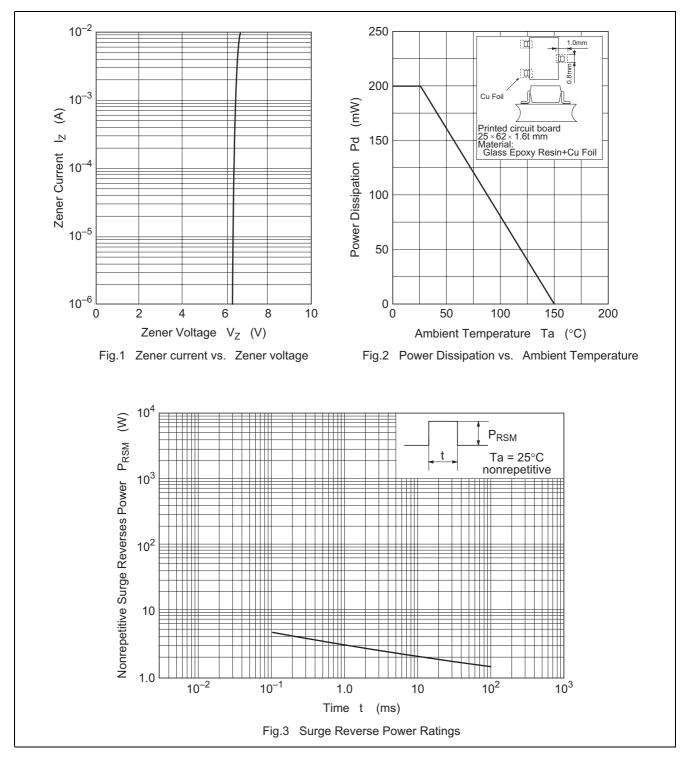
ltem	Symbol	Min	Тур	Max	Unit	Test Condition
Zener voltage	V _{-Z}	5.90	—	6.50	V	$I_Z = 5 \text{ mA}, 40 \text{ ms pulse}$
Reverse current	l _{.R} .	-	—	3	μA	V _{.R} = 5.5 V
Capacitance	С	-	4.0	4.5	pF	$V_{R} = 0 V, f = 1 MHz$
Dynamic resistance	r _d .	-	—	60	Ω	$I_Z = 5 \text{ mA}$
ESD-Capability *2	—	8	—	—	kV	C = 150 pF, R = 330 Ω , Both forward
						and reverse direction 10 pulse

Notes: 1. Per one device.

2. Failure criterion ; I_R > 3 μA at V_R = 5.5 V.

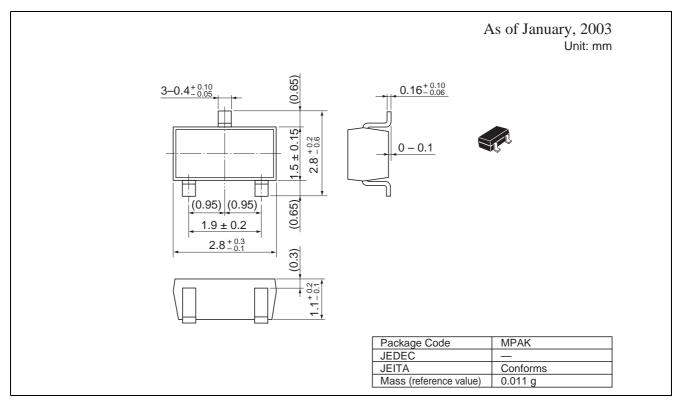


Main Characteristics





Package Dimensions





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